ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International a	Composition Dec 2005. IPC, Bannockt nd Pan-American co	c laration ourn, Illinois. A opyright conver	Il rights reserved untions.	under both	This docume level parts, the	ent is a declaration en declaration	on of the substand acompasses all lo	ces within the ma wer level materia	nufacturer list lls for which t	ed item. Note: if ne manufacturer	the item is an as has engineering	ssembly with low responsibility.	
				Form Type Distribute					s Materials an	ials and Mfg Information			
upplier Information													
ompany name*	Company unique ID			1	Unique ID Authority				Response Date*				
nsemi									2024-05-16				
Contact Name 7			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Phone - Representative*			Ema	Email - Representative*			
Product-Env-Stewards Pr			Product Enviro Compliance			NA			Pro	Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	Version Manufacturing Site		Site	Weight*	UOM	Unit Type	
	FSL138	FSL138MRTWDTU Power Swit		cher		2024-05-16	РВВ			2239.009	mg	Each	
Ianufacturing Proccess Info	ormation												
Terminal Plating / Grid Ar	Terminal Plating / Grid Array Material		erminal Base Alloy J-STD-020 MS		Rating	Peak Process Body Temperatur		ature Max Time	at Peak Temp	erature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0	С	30	se	conds 3			
omments													
or more information regarding ma	terial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.8	mg	Supplier	Silicon (Si)	7440-21-3		9.8	mg
Die Attach Epoxy	0.254	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0076	mg
			Supplier	Silver (Ag)	7440-22-4		0.2159	mg
			Supplier	Proprietary	Proprietary Data		0.0127	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0178	mg
Die Attach Solder	3.061	mg	Supplier	Silver (Ag)	7440-22-4		0.0765	mg
			А	Lead (Pb)	7439-92-1	7a	2.8314	mg
			Supplier	Tin (Sn)	7440-31-5		0.1531	mg
Lead Frame	1264.59	mg	Supplier	Silver (Ag)	7440-22-4		2.91	mg
			Supplier	Tin (Sn)	7440-31-5		1.55	mg
			Supplier	Copper (Cu)	7440-50-8		1260.0045	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1255	mg
Mold Compound-Black	950.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		114	mg
			Supplier	Carbon Black (C)	1333-86-4		4.75	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		831.25	mg
Plating	11.0	mg	Supplier	Tin (Sn)	7440-31-5		11	mg
Wire Bond - Cu	0.304	mg	Supplier	Copper (Cu)	7440-50-8		0.304	mg